Preferred Device

Ignition IGBT 15 Amps, 350 Volts N-Channel TO-220 and D²PAK

This Logic Level Insulated Gate Bipolar Transistor (IGBT) features monolithic circuitry integrating ESD and Over–Voltage clamped protection for use in inductive coil drivers applications. Primary uses include Ignition, Direct Fuel Injection, or wherever high voltage and high current switching is required.

- Ideal for Coil–On–Plug, IGBT–On–Coil, or Distributorless Ignition System Applications
- High Pulsed Current Capability up to 50 A
- Gate–Emitter ESD Protection
- Temperature Compensated Gate–Collector Voltage Clamp Limits Stress Applied to Load
- Integrated ESD Diode Protection
- Low Threshold Voltage to Interface Power Loads to Logic or Microprocessor Devices
- Low Saturation Voltage
- Optional Gate Resistor (RG)

MAXIMUM RATINGS ($-55^{\circ}C \le T_J \le 175^{\circ}C$ unless otherwise noted)

-			
Rating	Symbol	Value	Unit
Collector-Emitter Voltage	VCES	380	V _{DC}
Collector–Gate Voltage	VCER	380	V _{DC}
Gate-Emitter Voltage	VGE	22	V _{DC}
Collector Current–Continuous @ T _C = 25°C – Pulsed	IC	15 50	A _{DC} A _{AC}
ESD (Human Body Model) R = 1500 Ω , C = 100 pF	ESD	8.0	kV
ESD (Machine Model) $R = 0 \Omega$, $C = 200 pF$	ESD	800	V
Total Power Dissipation @ T _C = 25°C Derate above 25°C	PD	150 1.0	Watts W/°C
Operating and Storage Temperature Range	TJ, Tstg	–55 to 175	°C

UNCLAMPED COLLECTOR-TO-EMITTER AVALANCHE CHARACTERISTICS (–55°C \leq TJ \leq 175°C)

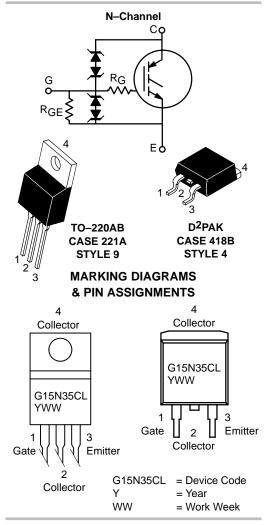
Characteristic	Symbol	Value	Unit
Single Pulse Collector–to–Emitter Avalanche Energy	EAS		mJ
$V_{CC} = 50 \text{ V}, \text{ V}_{GE} = 5.0 \text{ V}, \text{ Pk I}_{L} = 17.4 \text{ A}, \text{ L}$ = 2.0 mH, Starting T _{.I} = 25°C		300	
$V_{CC} = 50 \text{ V}, V_{GE} = 5.0 \text{ V}, \text{Pk I}_{L} = 14.2 \text{ A}, \text{L}$ = 2.0 mH, Starting T _J = 150°C		200	
Reverse Avalanche Energy $V_{CC} = 100 \text{ V}, \text{ V}_{GE} = 20 \text{ V}, \text{ L} = 3.0 \text{ mH},$ $Pk \text{ I}_{L} = 25.8 \text{ A}, \text{ Starting } \text{ T}_{J} = 25^{\circ}\text{C}$	E _{AS(R)}	1000	mJ



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15 AMPERES 350 VOLTS (Clamped) VCE(on) @ 10 A = 1.8 V Max



ORDERING INFORMATION

Device	Package Shipping		
MGP15N35CL	TO-220	50 Units/Rail	
MGB15N35CLT4	D2PAK	800 Tape & Reel	

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS

Characteristic		Symbol	Value	Unit
Thermal Resistance, Junction to Case		R _{θJC}	1.0	°C/W
Thermal Resistance, Junction to Ambient	TO-220	$R_{\theta}JA$	62.5	
	D ² PAK (Note 1.)	$R_{ extsf{ heta}JA}$	50	
Maximum Lead Temperature for Soldering Purposes, 1	1/8" from case for 5 seconds	ΤL	275	°C

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Test Conditions	Temperature	Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Collector-Emitter Clamp Voltage	BVCES	I _C = 2.0 mA	T _J = −40°C to 150°C	320	350	380	V _{DC}
		I _C = 10 mA	T _J = −40°C to 150°C	330	360	380	
Zero Gate Voltage Collector Current	ICES		TJ = 25°C	-	1.5	20	μA _{DC}
		V _{CE} = 300 V, V _{GE} = 0 V	TJ = 150°C	-	10	40*	
		6	TJ = −40°C	-	0.7	1.5	
Reverse Collector–Emitter Leakage Current	IECS		TJ = 25°C	-	0.35	1.0	mA
	V _{CE} = -24 V	$V_{CE} = -24 V$	TJ = 150°C	-	8.0	15*	
			$T_J = -40^{\circ}C$	-	0.05	0.5	
Reverse Collector–Emitter Clamp Voltage	BVCES(R)	CES(R)	T _J = 25°C	25	33	50	V _{DC}
		I _C = –75 mA	T _J = 150°C	25	36	50	
			$T_J = -40^{\circ}C$	25	30	50	
Gate-Emitter Clamp Voltage	BVGES	IG = 5.0 mA	T _J = −40°C to 150°C	17	20	22	V _{DC}
Gate-Emitter Leakage Current	IGES	V _{GE} = 10 V	T _J = −40°C to 150°C	384	600	1000	μA _{DC}
Gate Resistor (Optional)	RG	_	T _J = −40°C to 150°C	-	70	-	Ω
Gate Emitter Resistor	R _{GE}	_	T _J = -40°C to 150°C	10	16	26	kΩ

ON CHARACTERISTICS (Note 2.)

Gate Threshold Voltage	VGE(th)		TJ = 25°C	1.4	1.7	2.0	VDC
		I _C = 1.0 mA, V _{GE} = V _{CE}	T _J = 150°C	0.75	1.1	1.4	
			$T_J = -40^{\circ}C$	1.6	1.9	2.1*	
Threshold Temperature Coefficient (Negative)	-	-	-	-	4.4	-	mV/°C

1. When surface mounted to an FR4 board using the minimum recommended pad size.

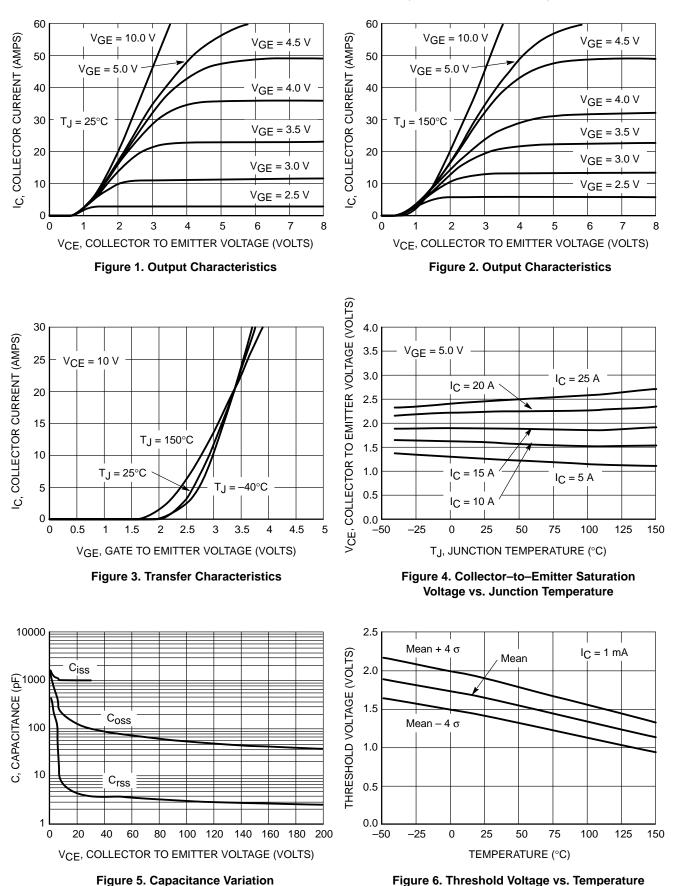
2. Pulse Test: Pulse Width \leq 300 μ S, Duty Cycle \leq 2%.

*Maximum Value of Characteristic across Temperature Range.

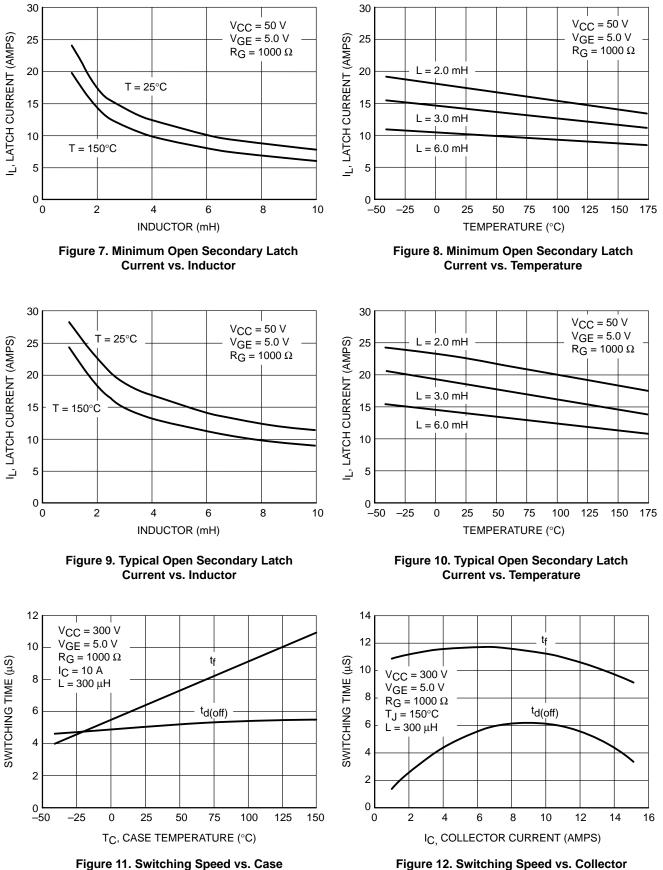
ELECTRICAL CHARACTERISTICS (continued)

Characteristic	Symbol	Test Conditions	Temperature	Min	Тур	Max	Unit
ON CHARACTERISTICS (continued) (Note 3.)						
Collector-to-Emitter On-Voltage	V _{CE(on)}		TJ = 25°C	1.0	1.3	1.6	V _{DC}
		I _C = 6.0 A, V _{GE} = 4.0 V	TJ = 150°C	0.9	1.2	1.5	
		-GL	TJ = −40°C	1.1	1.4	1.7*	
			TJ = 25°C	1.3	1.6	1.9	
		I _C = 10 A, V _{GF} = 4.0 V	TJ = 150°C	1.2	1.5	1.8	
		-GL -	TJ = −40°C	1.3	1.6	1.9*	
			TJ = 25°C	1.6	1.95	2.25	
		I _C = 15 A, V _{GF} = 4.0 V	TJ = 150°C	1.7	2.0	2.3*	
		IGL	TJ = −40°C	1.6	1.9	2.2	
			TJ = 25°C	1.9	2.2	2.5	
		I _C = 20 A, V _{GF} = 4.0 V	TJ = 150°C	2.1	2.4	2.7*	
		GL	TJ = −40°C	1.85	2.15	2.45	
			TJ = 25°C	2.1	2.5	2.9	
		I _C = 25 A, V _{GE} = 4.0 V	TJ = 150°C	2.5	2.9	3.3*	
		GL	TJ = −40°C	2.0	2.4	2.8	
Collector-to-Emitter On-Voltage	VCE(on)	I_{C} = 10 A, V_{GE} = 4.5 V	TJ = 150°C	-	1.5	1.8	V _{DC}
Forward Transconductance	gfs	V_{CE} = 5.0 V, I _C = 6.0 A	$T_J = -40^{\circ}C$ to $150^{\circ}C$	8.0	15	25	Mhos
OYNAMIC CHARACTERISTICS							
Input Capacitance	CISS			-	1000	1300	pF
Output Capacitance	COSS	V _{CC} = 25 V, V _{GE} = 0 V f = 1.0 MHz	T _J = -40°C to 150°C	-	100	130	
Transfer Capacitance	C _{RSS}	1 - 1.0 With2	100 0	-	5.0	8.0	
WITCHING CHARACTERISTICS (N	ote 3.)						-
Turn–Off Delay Time (Inductive)	^t d(off)	$V_{CC} = 300 \text{ V}, \text{ I}_{C} = 6.5 \text{ A}$	TJ = 25°C	-	4.0	10	μSec
		$R_G = 1.0 \text{ k}\Omega, L = 300 \mu\text{H}$	TJ = 150°C	-	4.5	10	
Fall Time (Inductive)	t _f	$V_{CC} = 300 \text{ V}, \text{ I}_{C} = 6.5 \text{ A}$	TJ = 25°C	-	7.0	10	
		$R_{G} = 1.0 \text{ k}\Omega, L = 300 \mu\text{H}$	TJ = 150°C	-	10	15*	
Turn–Off Delay Time (Resistive)	^t d(off)	$V_{CC} = 300 \text{ V}, \text{ I}_{C} = 6.5 \text{ A}$	TJ = 25°C	-	4.0	10	μSec
		$R_{G} = 1.0 \text{ k}\Omega, R_{L} = 46 \Omega,$	TJ = 150°C	-	4.5	10	
Fall Time (Resistive)	t _f	$V_{CC} = 300 \text{ V}, \text{ I}_{C} = 6.5 \text{ A}$	TJ = 25°C	-	13	20	
		R_{G} = 1.0 kΩ, R_{L} = 46 Ω,	TJ = 150°C	1	16	20	
Turn–On Delay Time	^t d(on)	V _{CC} = 10 V, I _C = 6.5 A	TJ = 25°C	-	1.0	1.5	μSec
	- (-)	$R_{G} = 1.0 \text{ k}\Omega, R_{L} = 1.5 \Omega$	TJ = 150°C	-	1.0	1.5	
Rise Time	tr	V _{CC} = 10 V, I _C = 6.5 A	TJ = 25°C	-	4.5	6.0	
		$R_{G} = 1.0 \text{ k}\Omega, R_{L} = 1.5 \Omega$		-	5.0	6.0	

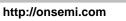
3. Pulse Test: Pulse Width \leq 300 µS, Duty Cycle \leq 2%. *Maximum Value of Characteristic across Temperature Range.



TYPICAL ELECTRICAL CHARACTERISTICS (unless otherwise noted)



Temperature



Current

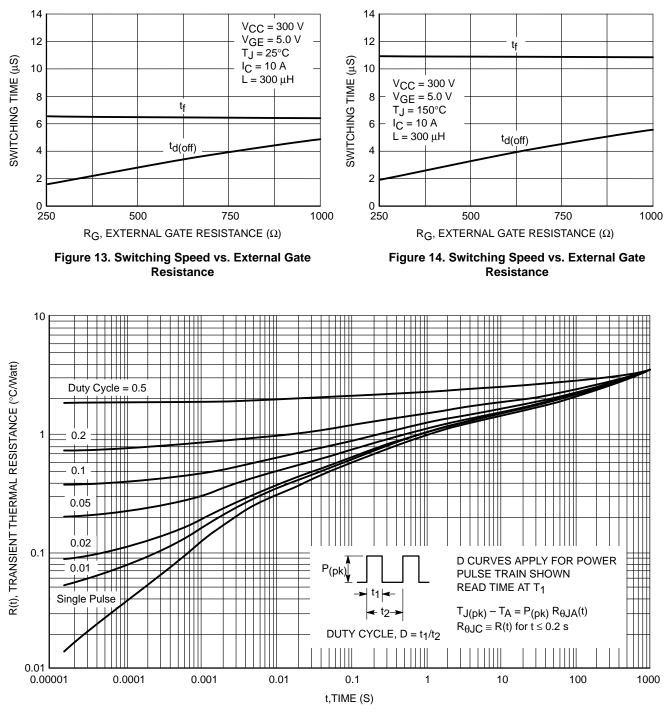


Figure 15. Transient Thermal Resistance (Non–normalized Junction–to–Ambient mounted on fixture in Figure 16)

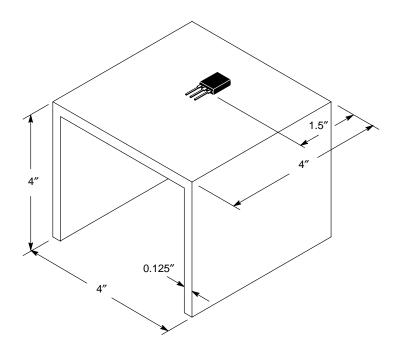


Figure 16. Test Fixture for Transient Thermal Curve (48 square inches of 1/8" thick aluminum)

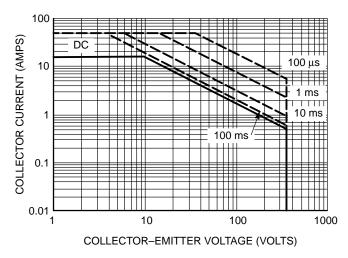


Figure 17. Single Pulse Safe Operating Area (Mounted on an Infinite Heatsink at $T_C = 25^{\circ}C$)

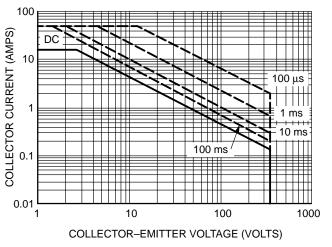


Figure 18. Single Pulse Safe Operating Area (Mounted on an Infinite Heatsink at $T_C = 125^{\circ}C$)

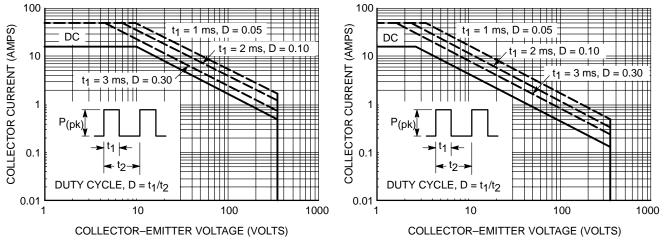
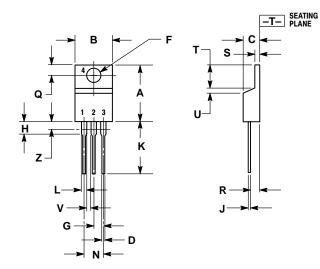


Figure 19. Pulse Train Safe Operating Area (Mounted on an Infinite Heatsink at $T_C = 25^{\circ}C$)



PACKAGE DIMENSIONS

TO-220 THREE-LEAD TO-220AB CASE 221A-09 **ISSUE AA**



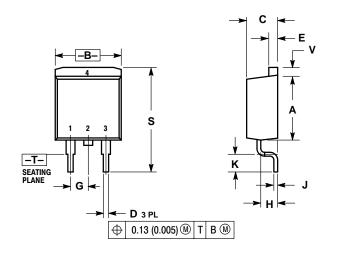
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
۷	0.045		1.15	
Z		0.080		2.04

STYLE 9: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

PACKAGE DIMENSIONS

D²PAK CASE 418B-03 ISSUE D



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTERVI UNG DIMENSION: INCH.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
Е	0.045	0.055	1.14	1.40
G	0.100 BSC		2.54	BSC
Η	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
S	0.575	0.625	14.60	15.88
٧	0.045	0.055	1.14	1.40

STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

<u>Notes</u>

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